TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSII<sup>.5</sup>)

# 2SK1120

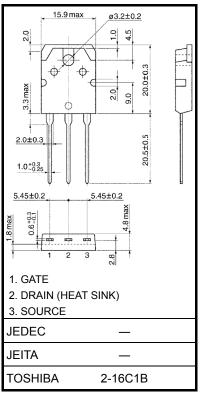
#### DC-DC Converter and Motor Drive Applications

Unit: mm

• Low drain-source ON resistance : RDS (ON) =  $1.5 \Omega$  (typ.) • High forward transfer admittance :  $|Y_{fs}| = 4.0 S$  (typ.) • Low leakage current : IDSS =  $300 \mu A$  (max) (VDS = 800 V) • Enhancement mode :  $V_{th} = 1.5 \sim 3.5 V$  (VDS = 10 V, ID = 1 mA)

### Absolute Maximum Ratings (Ta = 25°C)

| Characteris                                  | etics          | Symbol           | Rating  | Unit |  |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage                         |                | $V_{DSS}$        | 1000    | V    |  |
| Drain-gate voltage (R <sub>GS</sub> = 20 kΩ) |                | $V_{DGR}$        | 1000    | ٧    |  |
| Gate-source voltage                          |                | $V_{GSS}$        | ±20     | ٧    |  |
| Drain current                                | DC (Note 1)    | ΙD               | 8       | Α    |  |
|  | Pulse (Note 1) | $I_{DP}$         | 24      | Α    |  |
| Drain power dissipation                      | r (Tc = 25°C)  | $P_{D}$          | 150     | W    |  |
| Channel temperature                          |                | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature range                    |                | T <sub>stg</sub> | -55~150 | °C   |  |



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

| Characteristics                        | Symbol                 | Max   | Unit |
|--|------------------------|-------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 0.833 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 50    | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

This transistor is an electrostatic-sensitive device.

Please handle with caution.

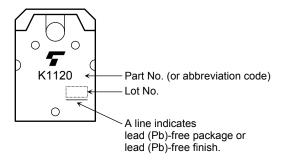
# **Electrical Characteristics (Ta = 25°C)**

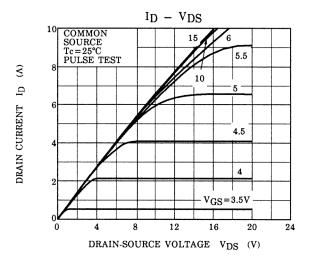
| Charac  | cteristics      | Symbol               | Test Condition   | Min  | Тур. | Max  | Unit |
|---|-----------------|----------------------|--|------|------|------|------|
| Gate leakage cu                                 | rrent           | I <sub>GSS</sub>     | V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V                             | _    | _    | ±100 | nA   |
| Drain cut-off cu                                | rrent           | I <sub>DSS</sub>     | V <sub>DS</sub> = 800 V, V <sub>GS</sub> = 0 V                             | _    | _    | 300  | μΑ   |
| Drain-source br                                 | eakdown voltage | V (BR) DSS           | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V                              | 1000 | _    | _    | V    |
| Gate threshold v                                | voltage         | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA                              | 1.5  | _    | 3.5  | V    |
| Drain-source O                                  | N resistance    | R <sub>DS</sub> (ON) | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A                               | _    | 1.5  | 1.8  | Ω    |
| Forward transfer                                | admittance      | Y <sub>fs</sub>      | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 4 A                               | 2.0  | 4.0  | _    | S    |
| Input capacitano                                | :e              | C <sub>iss</sub>     |  | _    | 1300 | _    |      |
| Reverse transfe                                 | r capacitance   | C <sub>rss</sub>     | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz                   |      | 100  | _    | pF   |
| Output capacitance                              |                 | Coss                 | ]  |      | 180  | _    |      |
| Switching time                                  | Rise time       | t <sub>r</sub>       | V <sub>GS</sub> <sub>0V</sub> V <sub>OUT</sub> R <sub>L</sub> = 100Ω       | _    | 25   | _    | - ns |
|   | Turn-on time    | t <sub>on</sub>      |  | _    | 40   | _    |      |
|   | Fall time       | t <sub>f</sub>       |  | _    | 20   | _    |      |
|   | Turn-off time   | t <sub>off</sub>     | $V_{DD} = 400V$ Duty $\leq 1\%$ , $t_w = 10 \mu s$                         | _    | 100  | _    |      |
| Total gate charge (Gate-source plus gate-drain) |                 | Qg                   |  | _    | 120  | _    |      |
| Gate-source charge                              |                 | Q <sub>gs</sub>      | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 8 \text{ A}$ | _    | 70   | _    | nC   |
| Gate-drain ("miller") charge                    |                 | Q <sub>gd</sub>      |  |      | 50   | _    |      |

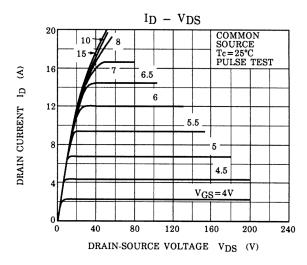
# Source-Drain Ratings and Characteristics (Ta = 25°C)

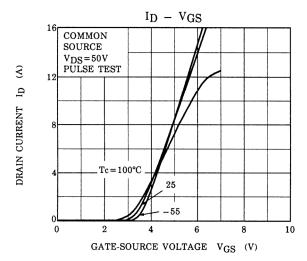
| Characteristics                           | Symbol           | Test Condition                               | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _  | _   | _    | 8    | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> |  | _   | _    | 24   | Α    |
| Forward voltage (diode)                   | $V_{DSF}$        | I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V | _   | _    | -1.9 | V    |

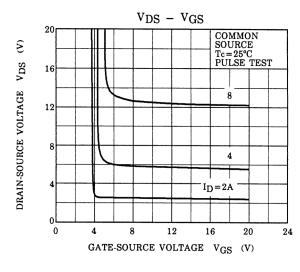
### Marking

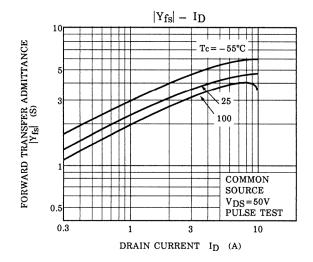


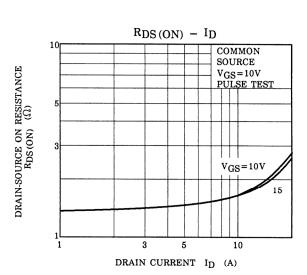




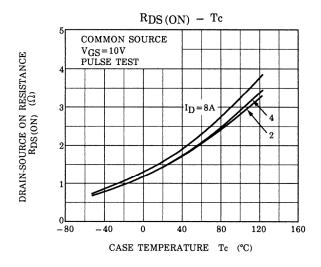


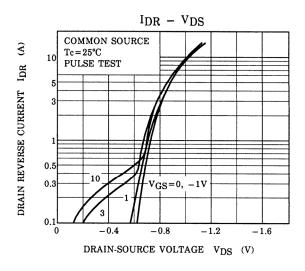


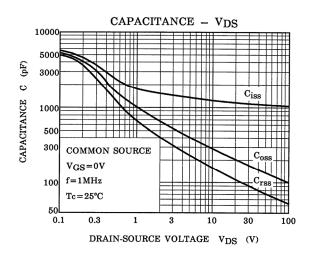


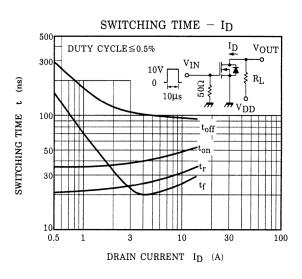


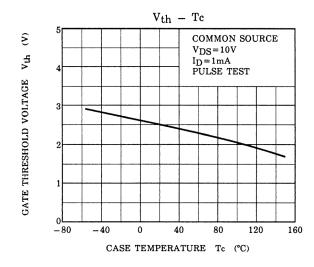
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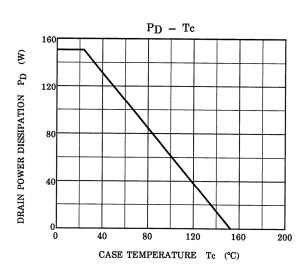


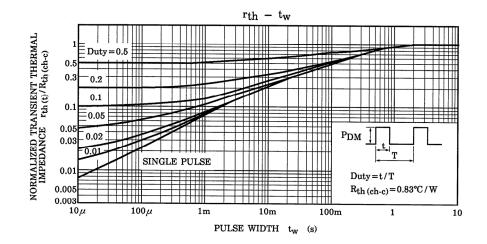


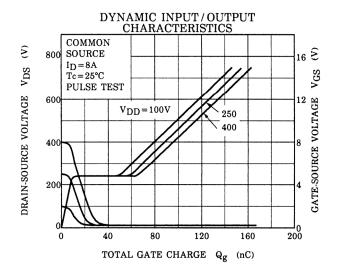


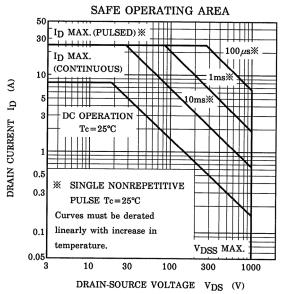












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